Vacuum Adsorption BGA Rework Equipment WDS 800A with Preheating Platform

Our Product Introduction

Basic Information

Place of Origin:	China
Brand Name:	WDS
Certification:	CE
Model Number:	WDS-800A
Minimum Order Quantity:	1 UNIT
Packaging Details:	Wooden case
Delivery Time:	8-15 working days
Payment Terms:	T/T, Western Union, MoneyGram
Supply Ability:	150 UNITS PER MONTH

Product Specification

Temperature Measuring Interface:	5pcs
Chip Zoom In And Out:	2-50times
PCB Thickness:	0.5~8mm
Apply Chip Size:	0.8*0.8~120*120mm
Applicable Minimum Chip Spacing:	0.15mm
Highlight:	**Preheating Platform BGA Rework Equipment**, **WDS 800A BGA Rework Equipment**, **Vacuum Adsorption BGA Rework Tools**

Product Description

Vacuum adsorption preheating platform Optical alignment Automatic BGA rework equipment WDS-800A

Specification and Feature:

1.Auto feed chips,auto pick up chips,auto blowing chips.
2.Hot air head and mounting head integration design, with auto soldering and desoldering functions.
3.Upper heaters adopt hot air system,heating faster,temperature evenness,cooling faster.(the temperature can be up to 50 to 80 centigrade)It can better meet technological requirements about lead-free soldering.Lower heaters adopt Hot air & IR mix heating. IR acts on the heating area directly; in the meanwhile, hot air works. They interact to heat quickly, and keep temperature even. (heating-up speed is up to 10 centigrade per minute.
4.Independent 3 heaters, upper and lower heaters can realize move synchronously and automatically,can reach IR every position.Lower heater zone can remove up and down,support PCB board. bottom pre-heating area along X/Y axis. Lower heater can move up/down and support PCB,auto-controlled by motors. It can realize the upper and lower heater able to move towards target BGA, without moving PCB.
5.PCB board adopts high accuracy slider to make sure the mount precision of BGA and PCB.
Unique bottom preheating table made of Germany-imported good quality heating materials plated IR tube & constant temperature glass anti-dazzle (heat-resist up to 1800 C), pre-heating area up to 500*420mm.
6.Preheating table, clamping device and cooling system can move integrally in X axis that make PCB locating & desoldering safer and conveniently.
7.X and Y axis adopt motor automatic control moving way to make the alignment faster and more convenient,make the most use of the equipment space,realization of repairing large area PCB with a smaller volume of equipment.The Max.plate size can reach 650*610mm,no repair dead corner.
8.Double rocker control the camera and upper and lower heating platform to make sure the alignment precision accuracy.
9.Inbuilt vacuum pump, rotate 360 in angel; fine-adjusting mounting suction nozzle.
10.Suction nozzle can detect BGA pickup and mounting height automatically with pressure controllable within 10 grams; zero pressure available to smaller BGA pickup and mounting.
11.Color high-resolution optical vision system, movable by hand in X/Y axis, with split vision, zoom in and fine-adjusting functions, aberration distinguish device included, auto-focus, software operation, 22x optical zoom; reworkable max. BGA size 80*80MM;
12.With 10 segments of temperature up (down) and 10 segments of constant temperature control,can save many segments of temperature.analyze the temperature parameter curves on the touch screen.
13.Many sizes of alloy nozzle, easy for replacement; can locate at all angle.
14.With 5 thermocouple ports, can real-time detect and analyze temperatures at multipoint.
15.With a solid operation display function to make the temperature control more reliable.
16.It can generate SMT standard temperature removing curve automatically in different regions and different environment temperature,don’t need to set curves manually, anybody can use it even without experience, realize machine intelligence
17.With the camera that can observe the melting point of solder side, it is convenient to determine the curve (this feature is optional items).

Technology Parameter

Total power	7600W
Upper heater power	1200W
Down heater power	1200W
IR heater power	5000W(2000W control)
Power Supply	(Double Phase)220V,50/60Hz
Locating Way	The V-shaped card slot fixes the PCB, the laser positioning light quickly locates, and the X and Y axes can be moved freely by the joystick control motor;
Number of drive motors and control area	6pcs(Control the X and Y axes of the heating head of the equipment to move, the X and Y axes of the alignment lens move, the heating head Z1 in the second temperature zone is electrically raised and lowered, and the Z axis of the upper heating head moves up and down)
Whether the preheating area of the third temperature zone can be moved	Yes (electrically moving)
Whether the upper and lower heating heads can be moved as a whole	Yes (electrically moving)
Whether the alignment lens can be automatically	Yes (automatic movement or manual controlled movement)
Whether the equipment has a suction and feeding device	Yes (standard)

The third temperature zone heating (preheating) method	Using bright infrared heating light tube imported from Germany (advantage: fast heating, when the equipment is heated normally, the temperature around the PCB motherboard and the temperature of the chip to be repaired will not form a large temperature difference, so as to ensure that the PCB motherboard will not be deformed or twisted phenomenon, which can better improve the soldering yield of the chip)
The second temperature zone control mode	Electric automatic lift
temperature control	High-precision K-type thermocouple (Ksensor) closed-loop control (Closed Loop), independent temperature measurement up and down, temperature control accuracy up to ± 1 degree
Electrical material selection	Taiwan touch screen + high precision temperature control module + Panasonic PLC + Panasonic servo + stepper driver
Max PCB size	630*480mm(Actual effective area, no dead angle for repair)
Min PCB size	10*10mm
Number of temperature measurement interfaces	5pcs
Chip zoom in and out	2-50X
PCBthickness	0.5~8mm
Applicable chips	0.8*0.8~80*80mm
Applicable chip minimum pitch	0.15mm
Mounting maximum load	800g
Mounting accuracy	±0.01mm
Machine Dimension	L970*W700*H830mm
Machine Weight	About 140KG

Shenzhen Wisdomshow Technology Co.,ltd

☎ +86 17727914291 ✉ Mia@wdsbga.cn bgaxraymachine.com

No.6,Haosi Western Industry,Shangjing Town,Bao'an District,Shenzhen,China